

Amendments to the Claims:

1. (Currently Amended) A power bus layout design ~~for improving the distribution of power supply current comprising:~~
a first electrically conductive layer including at least a first power bus and a second power bus,
a second electrically conductive layer including at least a first power bus and a second power bus,
an electrically insulating layer disposed between the first electrically conductive layer and the second electrically conductive layer,
a plurality of vias through said electrically insulating layer conductively connecting said first electrically conductive layer and said second electrically conductive layer and arranged such that said first power bus and said second power bus of said first electrically conductive layer are electrically connected; and
wherein ~~power supply current is provided on said first power bus and said second power bus of said first layer and on said first power bus and said second power bus of said second layer to reduce bottlenecking of said power supply current~~ said first and second electrically conductive layers and said vias are configured such that said second bus of said first electrically conductive layer is ultimately electrically connected to said first bus of said second electrically conductive layer yet said vias do not extend from said second bus of said first electrically conductive layer to said first bus of said second electrically conductive layer.

Serial No.: 10/648,054

Art Unit: 2826

Page 2

2. (Original) The bus layout design of claim 1, wherein said plurality of vias connecting said first electrically conductive layer and said second electrically conductive layer are arranged such that said first bus and said second bus of said second electrically conductive layer are electrically connected.
3. (Original) The bus layout design of claim 1, wherein said first and second bus of said first electrically conductive layer overlap said second bus of said second electrically conductive layer.
4. (Currently Amended) The bus layout design of claim 1, wherein said first and second buses of the first electrically conductive layer overlap said ~~first and second buses~~ bus of the second electrically conductive layer across the entire input/output width.
5. (Currently Amended) The bus layout design of claim 1, wherein said plurality of vias connecting said first electrically conductive layer and said second electrically conductive layer are arranged such that said first bus and said second bus of said second electrically conductive layer are electrically connected; and
- wherein said first and second ~~bus~~ buses of said first electrically conductive layer ~~overlaps~~ overlap said ~~first and~~ second bus of said second electrically conductive layer; across the entire input/output width.

Serial No.: 10/648,054

Art Unit: 2826

Page 3

6. (Currently Amended) A ~~power bus layout design for improving the distribution of power supply current~~ comprising:

a first electrically conductive layer including a plurality of power buses not conductively connected to each other on said first electrically conductive layer;

a second electrically conductive layer including a plurality of power buses not conductively connected to each other on said second electrically conductive layer;

an electrically insulating layer disposed between the first electrically conductive layer and the second electrically conductive layer;

wherein at least one bus on said first electrically conductive layer is conductively connected to at least ~~one bus~~ two buses on said second electrically conductive layer through said electrically insulating layer; and

wherein ~~power supply current is provided on said first power bus and said second power bus of said first layer and on said first power bus and said second power bus of said second layer to reduce bottlenecking of said power supply current~~ said at least one bus of said first electrically conductive layer does not overlap said at least two buses of said second electrically conductive layer.

7. (Cancelled)

Serial No.: 10/648,054
Art Unit: 2826
Page 4

8. (Original) The bus layout design of claim 6, further comprising a plurality of vias through said electrically insulating layer, said vias conductively connect at least one bus on said first electrically conductive layer to at least one bus on said second electrically conductive layer

9-11. (Cancelled)

12. (New) A bus layout design, comprising:

a first electrically conductive layer including at least a first bus and a second bus;

a second electrically conductive layer including at least a first bus and a second bus;

an electrically insulating layer disposed between the first electrically conductive layer and the second electrically conductive layer;

a plurality of vias extending through said electrically insulating layer conductively connecting said first electrically conductive layer and said second electrically conductive layer and;

wherein each said bus of said first electrically conductive layer does not overlap each said bus of said second electrically conductive layer.

13. (New) The bus design layout of claim 12, wherein said second bus of said first electrically conductive layer does not overlap said first bus of said second electrically conductive layer.

Serial No.: 10/648,054

Art Unit: 2826

Page 5